Pac Tech Asia Invests in Capacity Expansion of Malaysian Factory

Nauen, Germany – 2nd April 2024

Pac Tech Packaging Technologies GmbH (PacTech), a leading manufacturer of high-performance laser-assisted solder jetting and die bonding equipment, and a globally recognized wafer level packaging subcontractor, is proud to announce a \$10 million investment to enhance the capacity of its subsidiary, PacTech Asia Sdn. Bhd. (PacTech Asia), located in Penang, Malaysia.

With the semiconductor market poised for recovery in FY-2024 and a surge in demand anticipated from key customers, PacTech is strategically expanding its business footprint within the Southeast Asian supply chain. This expansion involves significant investments, including \$10 million in additional cleanroom space totaling 20,000 sqft, cutting-edge equipment, and factory automation. These enhancements to PacTech Asia's manufacturing capabilities will result in a substantial increase in bumping capacity, reaching up to 50,000 wafers per month.

Dr. Thorsten Teutsch, CEO of PacTech, expressed enthusiasm about the investment, stating, "We are thrilled to bolster our support for key customers by enhancing our capabilities and capacity. This investment reflects years of dedication, innovation, and hard work, which have earned us the trust and business of our long-term partners. Even amidst global economic challenges, our robust and successful business model continues to thrive."

About PacTech

PacTech is a global leader in advanced wafer bumping, packaging, and solder ball placement equipment. The company also offers plating chemistries and high-volume subcontractor bumping and die prep services for semiconductors, catering to diverse applications in consumer electronics, automotive, RF, and AI technologies. With manufacturing facilities in Germany (HQ), the USA, and Malaysia, PacTech is well-positioned to support the evolving needs of the semiconductor industry worldwide.

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